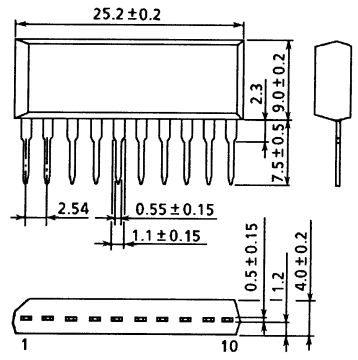
TOSHIBA Power MOS FET Module Silicon P Channel MOS Type (Four L^2-π-MOSV inOne)

MP4211

Industrial Applications

Unit: mm

High Power, High Speed Switching Applications
For Printer Head Pin Driver and Pulse Motor Driver
For Solenoid Driver



1, 10 SOURCE
2, 4, 6, 8 GATE
3, 5, 7, 9 DRAIN
(PIN 1 AND PIN 10 IS DISCONNECTED INTERNALLY)

JEDEC	—
JEITA	—
TOSHIBA	2-25A1C

Weight: 2.1 g (typ.)

- 4-V gate drivability
- Small package by full molding (SIP 10 pin)
- High drain power dissipation (4 devices operation)
  : P_T = 4 W (Ta = 25°C)
- Low drain-source ON resistance: $R_{DS\ (ON)}$ = 0.16 Ω (typ.)
- High forward transfer admittance: $|Y_{fs}|$ = 4.0 S (typ.)
- Low leakage current: I_{GSS} = ±10 μA (max) (V_{GS} = ±16 V)
  I_{DSS} = −100 μA (max) (V_{DS} = −60 V)
- Enhancement-mode: V_{th} = −0.8 to −2.0 V (V_{DS} = −10 V, I_D = −1 mA)

Maximum Ratings (Ta = 25°C)

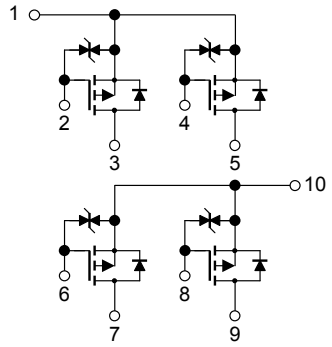
Characteristics		Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	−60	V
Drain-gate voltage (R_{GS} = 20 kΩ)		V_{DGR}	−60	V
Gate-source voltage		V_{GSS}	±20	V
Drain current	DC	I_D	−5	A
	Pulse	I_{DP}	−20	
Drain power dissipation (1-device operation, Ta = 25°C)		P_D	2.0	W
Drain power dissipation (- device operation, Ta = 25°C)		P_{DT}	4.0	W
Single pulse avalanche energy (Note 1)		E_{AS}	273	mJ
Avalanche current		I_{AR}	−5	A
Repetitive avalanche energy (Note 2)	1-device operation	E_{AR}	0.2	mJ
	4-device operation	E_{ART}	0.4	
Channel temperature		T_{ch}	150	°C
Storage temperature range		T_{stg}	−55 to 150	°C

Note 1: Condition for avalanche energy (single pulse) measurement
V_{DD} = −25 V, starting T_{ch} = 25°C, L = 14.84 mH, R_G = 25 Ω, I_{AR} = −5 A

Note 2: Repetitive rating; pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Please handle with caution.

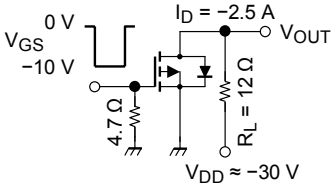
Array Configuration



Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance from channel to ambient (4-device operation, Ta = 25°C)	$\Sigma R_{th\ (ch\text{-}a)}$	31.2	°C/W
Maximum lead temperature for soldering purposes (3.2 mm from case for t = 10 s)	T_L	260	°C

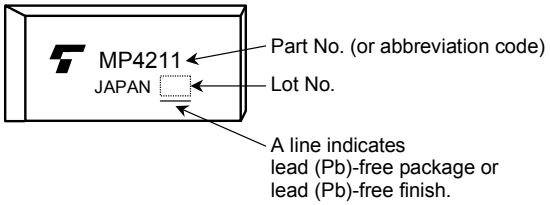
Electrical Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current		I_{GSS}	V_{GS} = ±16 V, V_{DS} = 0 V	—	—	±10	μA
Drain cut-off current		I_{DSS}	V_{DS} = −60 V, V_{GS} = 0 V	—	—	−100	μA
Drain-source breakdown voltage		$V_{(BR)\ DSS}$	I_D = −10 mA, V_{GS} = 0 V	−60	—	—	V
Gate threshold voltage		V_{th}	V_{DS} = −10 V, I_D = −1 mA	−0.8	—	−2.0	V
Drain-source ON resistance		$R_{DS\ (ON)}$	V_{GS} = −4 V, I_D = −2.5 A	—	0.24	0.28	Ω
			V_{GS} = −10 V, I_D = −2.5 A	—	0.16	0.19	
Forward transfer admittance		$\|Y_{fs}\|$	V_{DS} = −10 V, I_D = −2.5 A	2.0	4.0	—	S
Input capacitance		C_{iss}	V_{DS} = −10 V, V_{GS} = 0 V, f = 1 MHz	—	630	—	pF
Reverse transfer capacitance		C_{rss}		—	95	—	pF
Output capacitance		C_{oss}		—	290	—	pF
Switching time	Rise time	t_r		—	25	—	ns
	Turn-on time	t_{on}		—	45	—	
	Fall time	t_f		—	55	—	
	Turn-off time	t_{off}	V_{IN}: t_r, t_f < 5 ns, duty ≤ 1%, t_w = 10 μs	—	200	—	
Total gate charge (Gate-source plus gate-drain)		Q_g	V_{DD} ≈ −48 V, V_{GS} = −10 V, I_D = −5 A	—	22	—	nC
Gate-source charge		Q_{gs}		—	16	—	nC
Gate-drain (“miller”) charge		Q_{gd}		—	6	—	nC

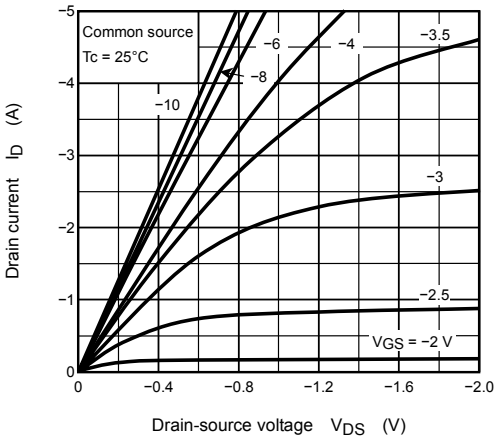
Source-Drain Diode Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Continuous drain reverse current	I_{DR}	—	—	—	−5	A
Pulse drain reverse current	I_{DRP}	—	—	—	−20	A
Diode forward voltage	V_{DSF}	I_{DR} = −5 A, V_{GS} = 0 V	—	—	1.7	V
Reverse recovery time	t_{rr}	I_{DR} = −5 A, V_{GS} = 0 V	—	80	—	ns
Reverse recovery charge	Q_{rr}	dI_{DR}/dt = 50 A/μs	—	0.1	—	μC

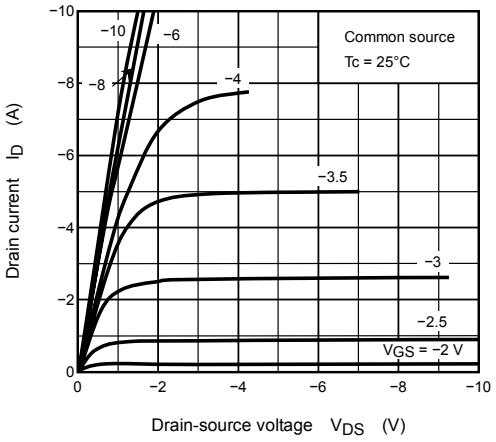
Marking



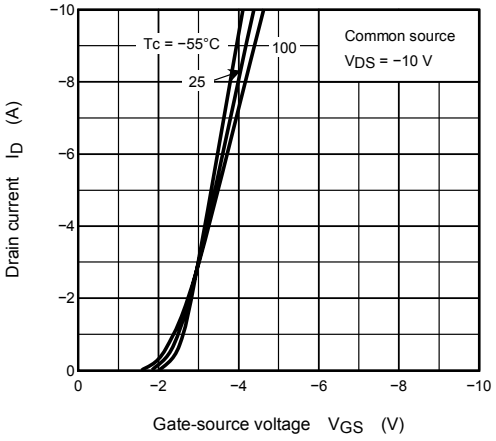
$I_D - V_{DS}$



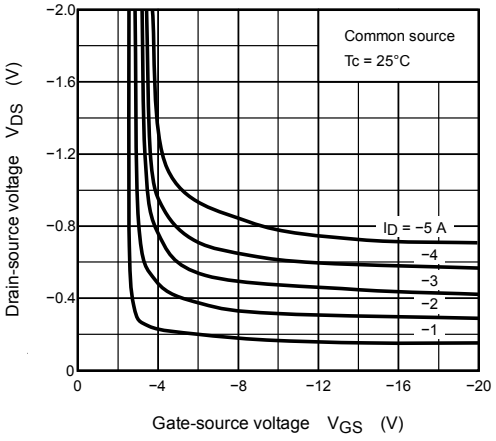
$I_D - V_{DS}$



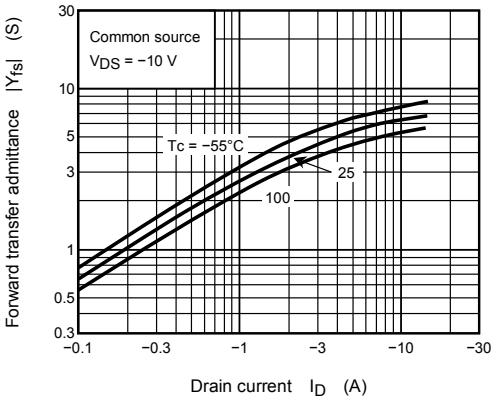
$I_D - V_{GS}$



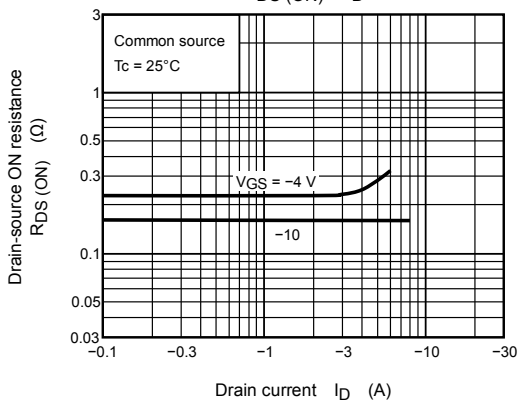
$V_{DS} - V_{GS}$



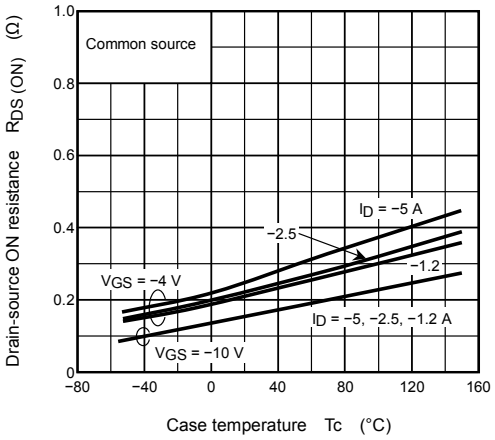
$|Y_{fs}| - I_D$



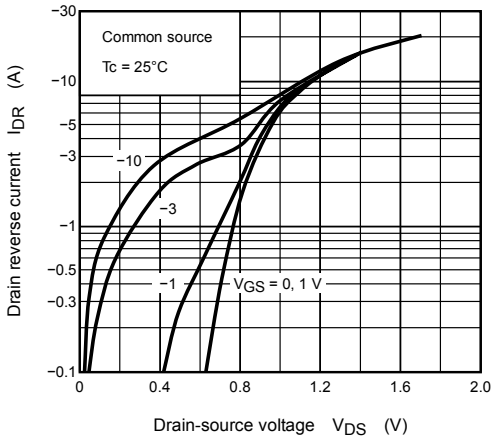
$R_{DS\ (ON)} - I_D$



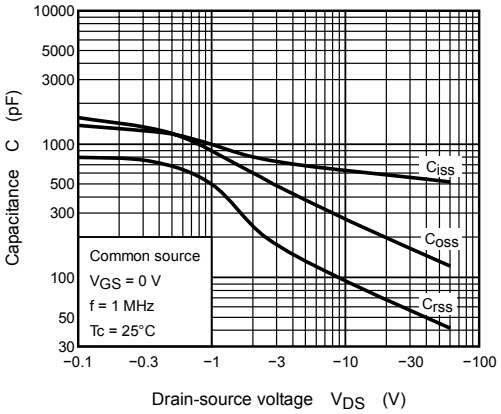
$R_{DS\ (ON)}$ – Tc



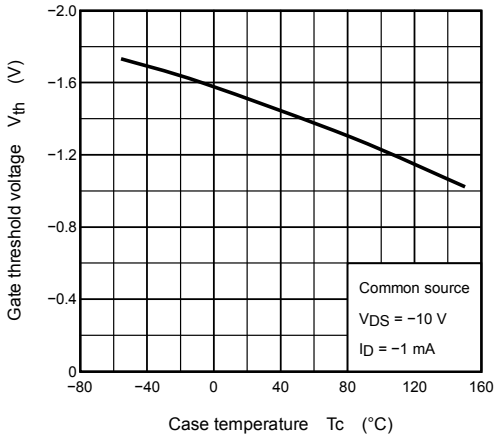
I_{DR} – V_{DS}



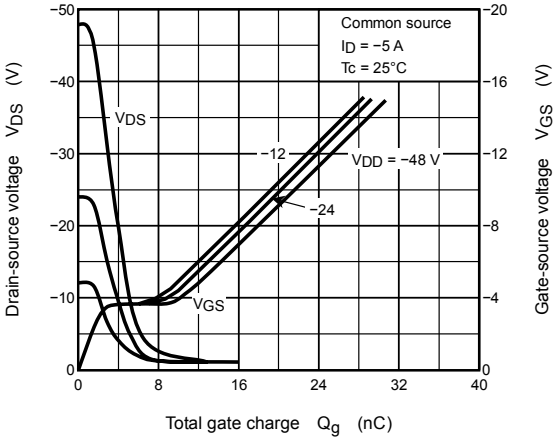
Capacitance – V_{DS}



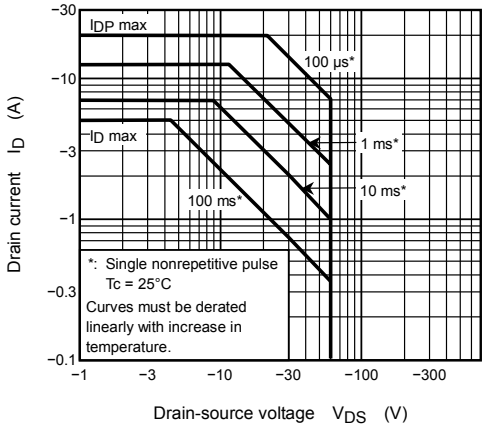
V_{th} – Tc



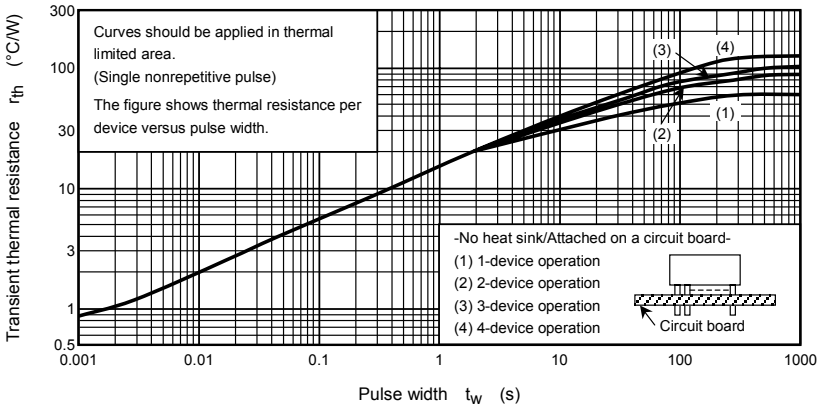
Dynamic Input/Output Characteristics



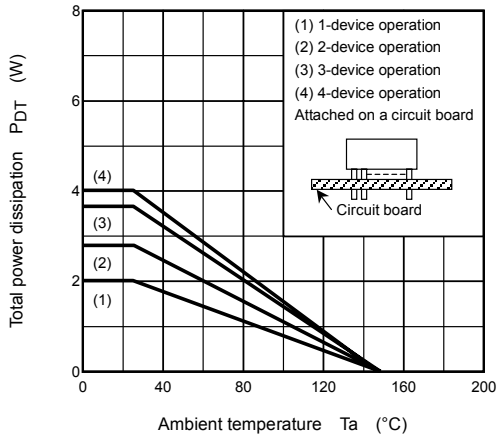
Safe Operating Area



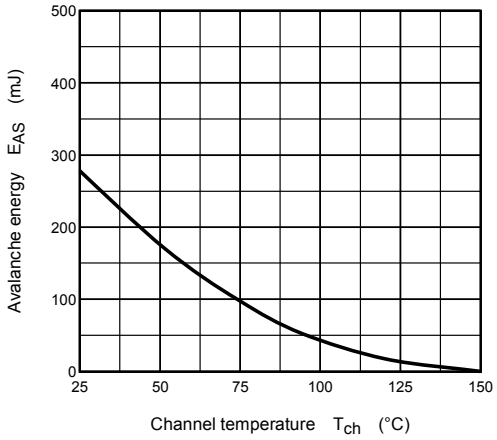
$r_{th} - t_w$



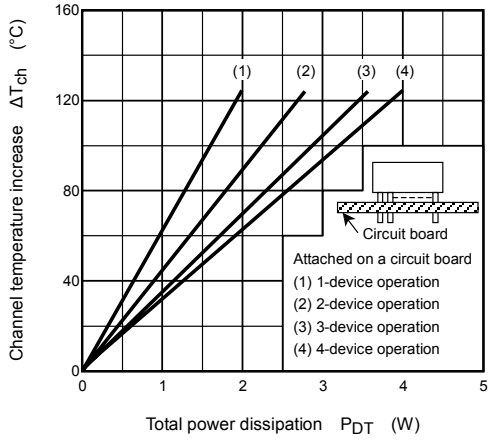
$P_{DT} - Ta$

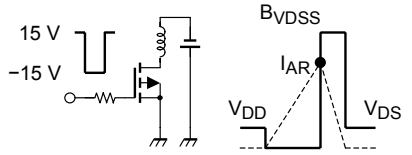


$E_{AS} - T_{ch}$



$\Delta T_{ch} - P_{DT}$





Peak I_{AR} = −5 A, R_G = 25 Ω
V_{DD} = −25 V, L = 14.84 mH

$$E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right)$$

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